PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5980181

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHE-JUI HSU	02/12/2020
CHUN-SHENG LU	02/12/2020
YING-FU TUNG	02/12/2020
MAO-CHANG YEN	02/12/2020
WAN-YU PENG	02/12/2020

RECEIVING PARTY DATA

Name:	WINBOND ELECTRONICS CORP.
Street Address:	NO. 8 KEYA 1ST RD., DAYA DISTRICT, CENTRAL TAIWAN SCIENCE PARK,
City:	TAICHUNG CITY
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16794525

CORRESPONDENCE DATA

Fax Number: (703)621-7155

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7036217140
Email: mailroom@mg-ip.com
Correspondent Name: MUNCY, GEISSLER, OLDS & LOWE, PC
Address Line 1: 4000 LEGATO ROAD, SUITE 310
Address Line 4: FAIRFAX, VIRGINIA 22033

ATTORNEY DOCKET NUMBER:	0941/3762PUS1
NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe McKinney Muncy/
DATE SIGNED:	02/25/2020

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Che-Jui HSU, Chun-Sheng LU, Ying-Fu TUNG, Mao-Chang YEN and Wan-Yu PENG hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR STRUCTURE AND METHOD FOR FORMING THE SAME

Filed: February 19, 2020 Serial No. 16/794,525
Executed on:

WHEREAS, Winbond Electronics Corp. of No. 8 Keya 1st Rd., Daya District, Central Taiwan Science Park, Taichung City, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Che-Jui Hsu
Che-Jui HSU

February 12, 2020
Date

Chun Sheng Lu
Chun-Sheng LU

February 12, 2020
Date

Ying Fu Tung
Ying-Fu TUNG

February 12, 2020
Date

ASSIGNMENT

Mao-Chang Yen
Mao-Chang YEN

February 12, 2020
Date

Wan-Yu PENG
Wan-Yu PENG

February 12, 2020
Date